# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT4178207

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
SEN-TAI YANG	08/20/2016

### **RECEIVING PARTY DATA**

Name:	ame: YUJING TECHNOLOGY CO., LTD.	
Street Address:	reet Address: NO. 66, LN. 50, DAREN RD., DAYUAN DIST.,	
City:	TAOYUAN CITY	
State/Country:	TAIWAN	
Postal Code:	337	

## **PROPERTY NUMBERS Total: 1**

Property Type	Number	
Application Number:	15370394	

## **CORRESPONDENCE DATA**

**Fax Number:** (801)708-0859

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

**Phone:** 4089609921

Email: linyun49@gmail.com
Correspondent Name: LINYUN CHENG
Address Line 1: 20775 NORADA CT

Address Line 4: SARATOGA, CALIFORNIA 95070

ATTORNEY DOCKET NUMBER:	19616103
NAME OF SUBMITTER:	LIN YUN CHENG
SIGNATURE:	/lin yun cheng/
DATE SIGNED:	12/09/2016

**Total Attachments: 1** 

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PATENT 504138363 REEL: 040698 FRAME: 0515

#### ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration, ASSIGNOR

ſ	Assignor's Name	Assignor's Residence and/or Address	Nationality
I	YANG, SEN-TAI	No.66, Ln. 50, Daren Rd., Dayuan Dist., Taoyuan City 337,	Taiwan, R.O.C.
		Taiwan (R.O.C.)	

hereby sells, assigns and transfers to ASSIGNEE

Assignee's Name	Assignee's Residence and/or Address	Nationality
YUJING	No.66, Ln. 50, Daren Rd., Dayuan Dist., Taoyuan City 337,	Taiwan. R.O.C
TECHNOLOGY CO	O., Taiwan (R.O.C.)	
LTD		

LID			<u></u>	
and the successors, assigns and legal representatives of the ASSIGNEE				
the entire right, title, and interest	est	an undivided	percent (%) interest	
in and to any and all improvements	s which are disclosed in the in	vention entitled: RESO	NANT HIGH	
CURRENT DENSITY T	RANSFORMER WI	TH IMPROVED	STRUCTURE	
, and which is found in				
(a) U.S. patent application execu	uted on 8/20/2016,			
(b) 🗓 U.S. patent application seria	d number 15/370,394	, filed on _1:	2/6/2016	
(c) U.S. patent number	, issu	ed on		
and, in and to, all Letters Patent to	o be obtained for said invention	on by the above application	on or any continuation, division,	
renewal, or substitute thereof, and a	as to Letters Patent any reissue	d or re-examination there	eof.	
ASSIGNOR hereby cover	iants that no assignment, sale	agreement or encumbra	nce has been or will be made or	
entered into which would conflict v	entered into which would conflict with this assignment;			
ASSIGNOR further covenants that ASSIGNOR will communicate to ASSIGNEE or its representatives any fact				
known to ASSIGNOR respecting t	known to ASSIGNOR respecting the invention, to testify in any legal proceedings, to sign all lawful papers, to execute all			
divisions, continuations, substitution	ons, renewal and reissue appli	eations, and to generally	do those things necessary to aid	
ASSIGNEE and its successors and	1 assigns to obtain and enforc	e proper protection for the	ne invention in the United States	
and in any and all foreign countries	š.			
Assignor's Signature	Printed Na	me and/or Title	Date Signed	
Hang, San Jai	YANC	, SEN-TAI (Inventor)	Aug. 20,20/2	

PATENT REEL: 040698 FRAME: 0516

Pat-Assignment (Rev. 11/2005)

**RECORDED: 12/09/2016** 

 $\boxtimes$  Total of 1 forms are submitted.